

L Number	Hits	Search Text	DB	Time stamp
1	282	((thin adj core) thincore coreless) with (substrate carrier pcb board)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/06 20:08
2	413	((thin adj core) thincore coreless) same (substrate carrier pcb board)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/06 20:08
3	477743	heat with (sink spreader dissipate metal dissipated dissipation dissipating radiate radiation radiated radiating slug stiffener)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/06 19:58
4	31	(heat with (sink spreader dissipate metal dissipated dissipation dissipating radiate radiation radiated radiating slug stiffener)) and (((thin adj core) thincore coreless) same (substrate carrier pcb board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/06 19:58
5	52	((thin adj core) thincore coreless) with (heat with (sink spreader dissipate metal dissipated dissipation dissipating radiate radiation radiated radiating slug stiffener))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/06 20:09
6	45	((thin adj core) thincore coreless) with (heat with (sink spreader dissipate metal dissipated dissipation dissipating radiate radiation radiated radiating slug stiffener))) not ((heat with (sink spreader dissipate metal dissipated dissipation dissipating radiate radiation radiated radiating slug stiffener)) and (((thin adj core) thincore coreless) same (substrate carrier pcb board)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/06 20:09